

### Product Description

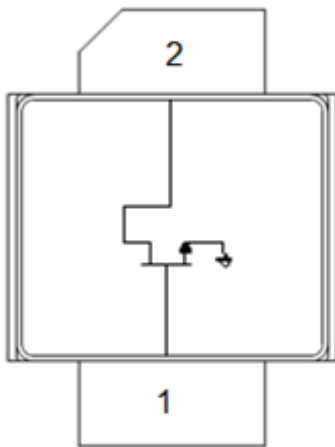
The QPD2194 is a discrete GaN on SiC HEMT which operates from 1.8-2.2 GHz. The device is a single stage pre-matched power amplifier transistor.

The QPD2194 can be used in Doherty architecture for the final stage of a base station power amplifier for macrocell high efficiency systems.

QPD2194 can deliver  $P_{SAT}$  of 371 W at +48 V operation.

Lead-free and ROHS compliant.

### Functional Block Diagram



2 Lead NI400 Package

### Product Features

- Operating Frequency Range: 1.8-2.2 GHz
- Operating Drain Voltage: +48 V
- Maximum Output Power ( $P_{SAT}$ ): 371 W
- Maximum Drain Efficiency: 78.8%
- Efficiency-Tuned P3dB Gain: 18.0 dB
- 2-lead, earless, ceramic flange NI400 package

### Applications

- W-CDMA / LTE
- Macrocell Base Station, B3-B1
- Active Antenna

### Ordering Information

Part No.	ECCN	Description
QPD2194S2	EAR99	Box (2 Samples Each)
QPD2194SQ	EAR99	Tray (25 Samples)
QPD2194SR	EAR99	Reel (100 Samples)
QPD2194PCB4B01	EAR99	1.805-2.17 GHz Eval. Board



# QPD2194

## 300 W, 48 V, 1.8-2.2 GHz GaN RF Power Transistor

### Absolute Maximum Ratings

Parameter	Value / Range
Gate Current ( $I_G$ )	-48 to 48 mA
Drain Voltage ( $V_D$ )	+55 V
Peak RF Input Power	44 dBm
VSWR Mismatch, P1dB Pulse (10 % duty cycle, 100 $\mu$ width), T = 25 °C	10:1
Storage Temperature	-65 to +150°C

Operation of this device outside the parameter ranges given above may cause permanent damage.

### Recommended Operating

Parameter	Min	Typ	Max	Units
Operating Temperature	-40	-	-	°C
Gate Voltage ( $V_G$ )	-	-2.7	-	V
Drain Voltage ( $V_D$ )	-	48	-	V
Quiescent Current ( $I_{DQ}$ )	-	600	-	mA
$T_{CH}$ for >10 <sup>6</sup> hours MTTF	-	-	250	°C

Electrical performance is measured under conditions noted in the electrical specifications table. Specifications are not guaranteed over all recommended operating conditions.

### RF Characterization

Parameter	Conditions	Min	Typ	Max	Units
Frequency Range		1805	-	2170	MHz
Quiescent Current		-	600	-	mA
Linear Gain		-	19.1	-	dB
P3dB		-	55.0	-	dBm
Drain Efficiency	P3dB	-	60.0	-	%

Test conditions unless otherwise noted:  $V_D = +48$  V,  $I_{DQ} = 600$  mA, T = 25°C, Pulsed CW (10% duty cycle, 100  $\mu$ s width) on Class AB single-ended EVB at 1880 MHz

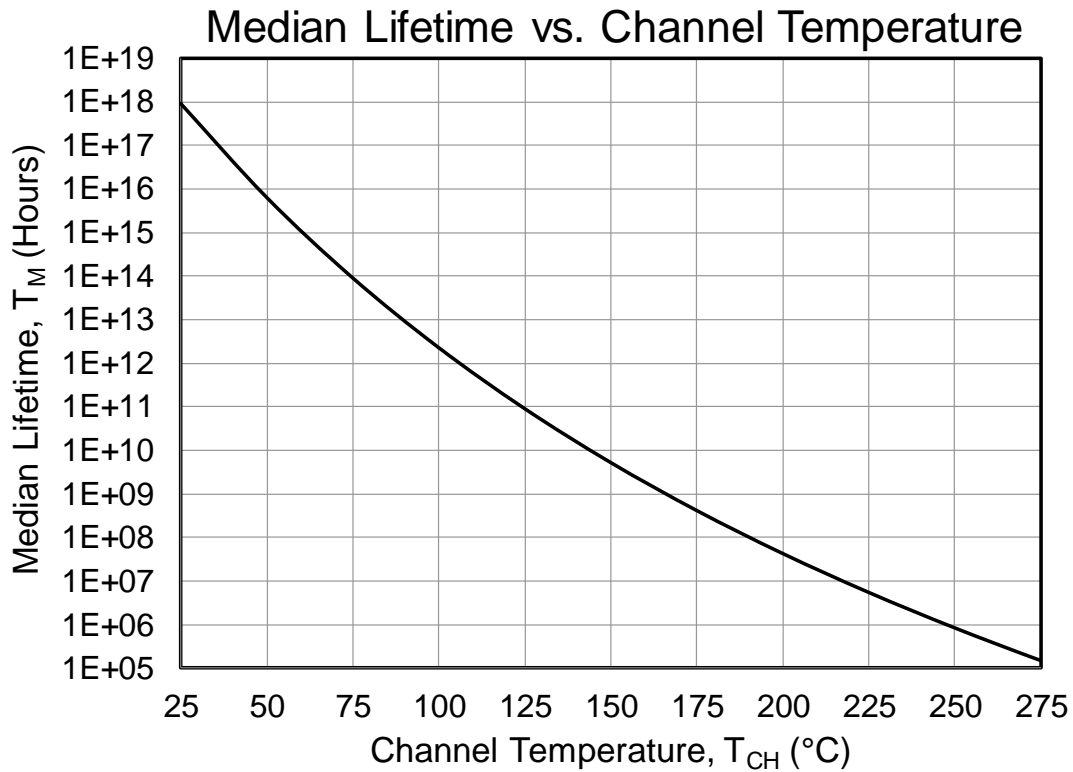
### Thermal and Reliability Information

Parameter	Test Conditions	Value	Units
Carrier Amplifier Thermal Resistance at Average Power ( $\theta_{JC}$ )	$T_{CASE} = 85^{\circ}C$ , $T_{CH} = 152^{\circ}C$ , CW: $P_{DISS} = 60W$ , $P_{OUT} = 90W$	1.12	$^{\circ}C/W$

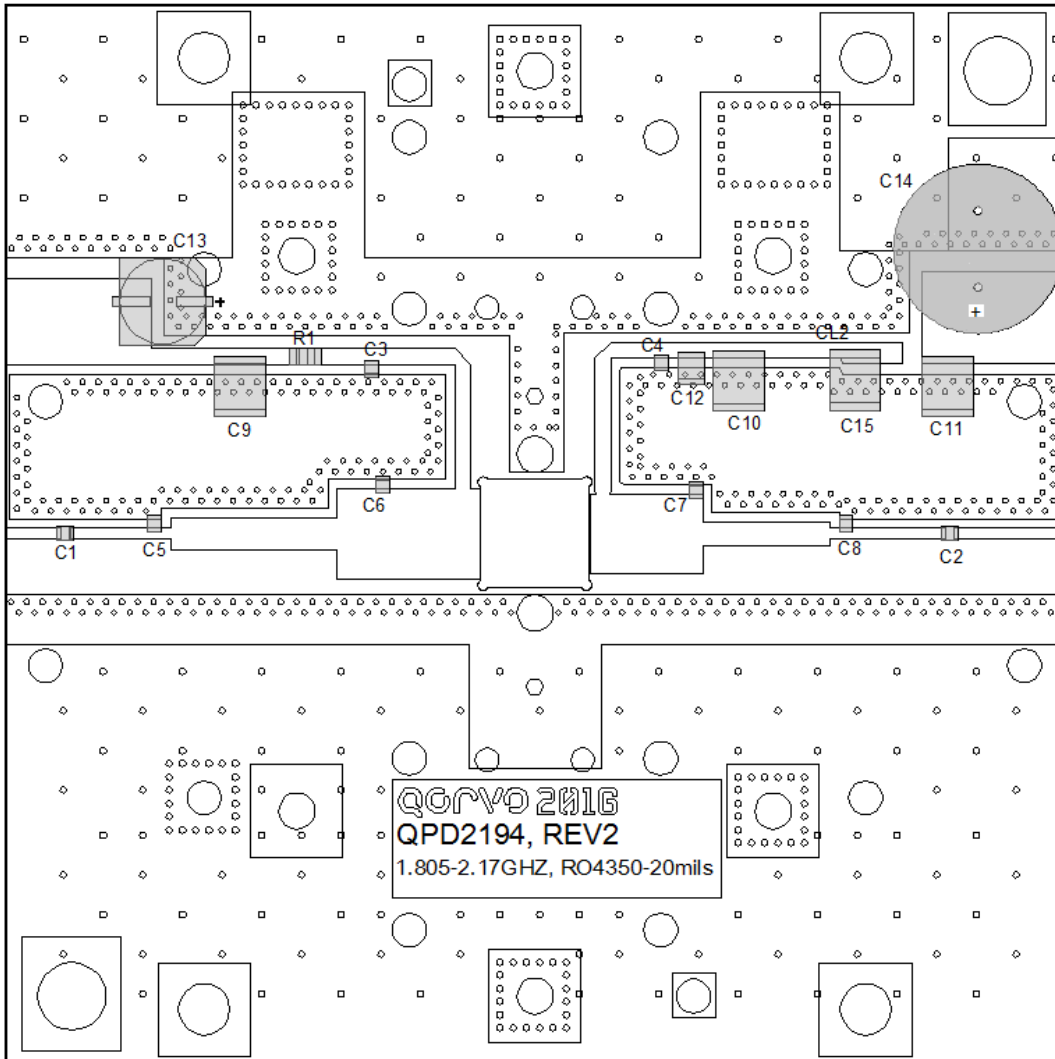
Notes:

1. Thermal resistance measured to package backside.
2. Based on expected carrier amplifier efficiency of Doherty.
3.  $P_{OUT}$  assumes 20% peaking amplifier contribution of total average Doherty rated power.

### Median Lifetime



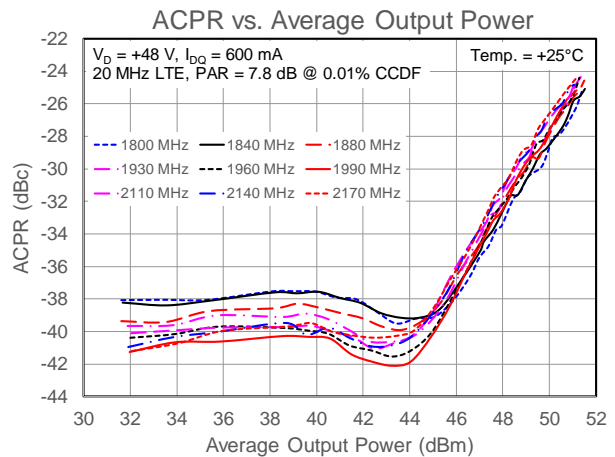
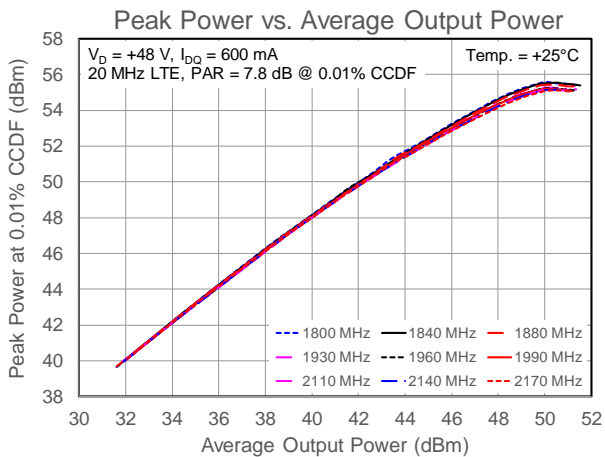
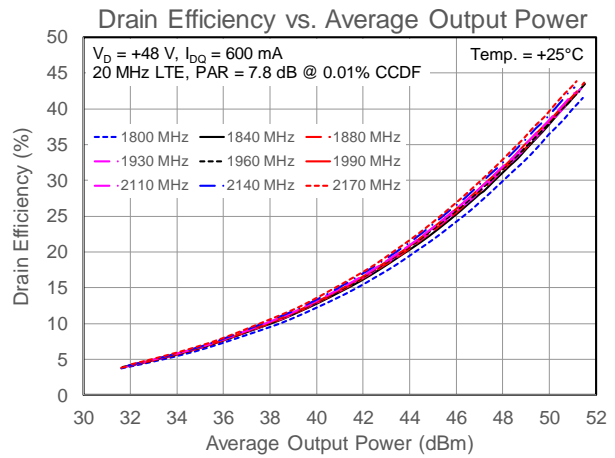
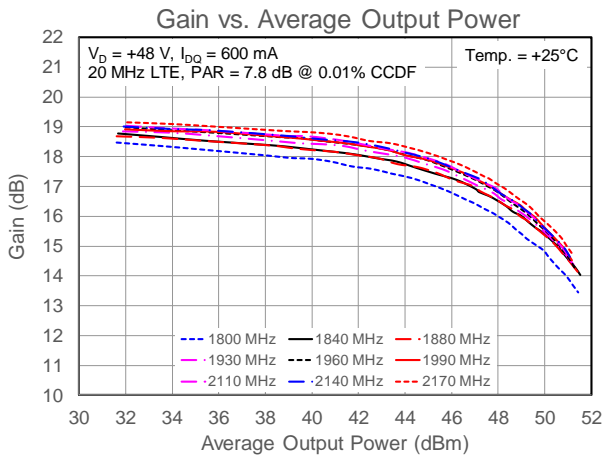
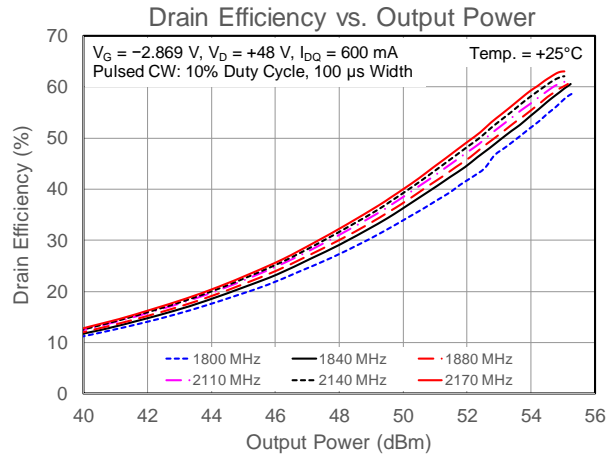
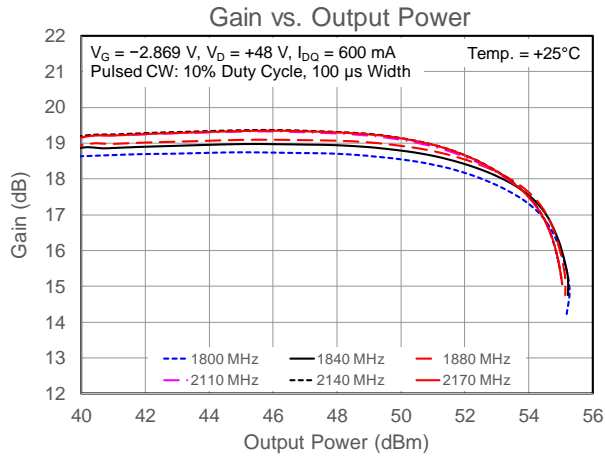
## Single-Ended Evaluation Board Layout



## Bill of Materials

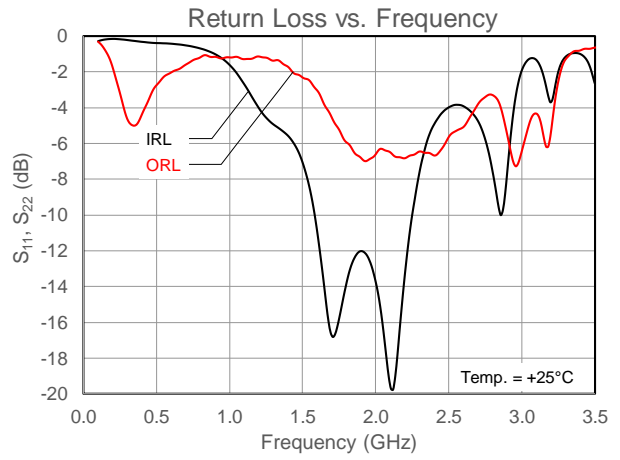
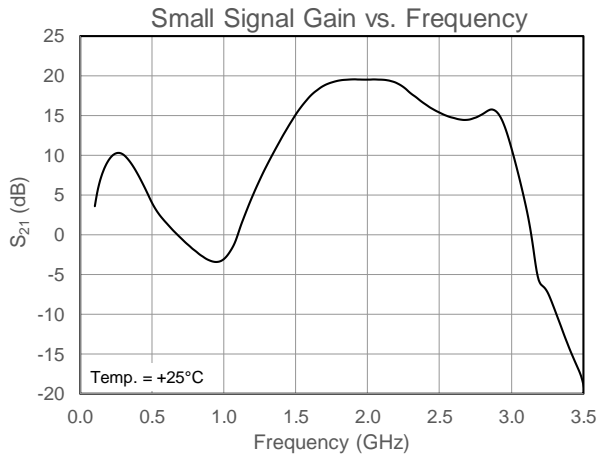
Reference Des.	Value	Description	Manuf.	Part Number
C1, C2, C3, C4	33 pF	Capacitor, 33 pF, 5%, 250 V	ATC	ATC800A330JT
C5	1.2 pF	Capacitor, 1.2 pF, ±0.1 pF, 250 V	ATC	ATC800A1R2BT250X
C6	1.9 pF	Capacitor, 1.9 pF, ±0.1 pF, 250 V	ATC	ATC800A1R9BT250X
C7	2.2 pF	Capacitor, 2.2 pF, ±0.1 pF, 250 V	ATC	ATC800A2R2BT250X
C8	0.8 pF	Capacitor, 0.8 pF, ±0.1 pF, 250 V	ATC	ATC800A0R8BT250X
C9, C10, C11, C15	4.7 μF	Capacitor, 4.7 μF, 10%, 100 V, X7R	Murata	GRM55ER72A475KA01L
C12	1 μF	Capacitor, 1 μF, 10%, 100 V, X7R	Murata	GRM32NR72A104KA01L
C13	100 μF	Capacitor, 100 μF, ±20%, 50 V, electrolytic	Panasonic	EEE-1HA101UAP
C14	220 μF	Capacitor, 220 μF, 20%, 100 V, electrolytic	Cornell	AFK227M2AR44T-F
R1	10 Ω	Resistor, 10 Ω, 1%, 1/4 W, 1206	Panasonic	ERJ-8ENF10R0V

### Single-Ended Evaluation Board Performance Plots



Test conditions unless otherwise noted:  $V_D = +48\text{ V}$ ,  $I_{DQ} = 600\text{ mA}$ ,  $T = 25^\circ\text{C}$ , on Class AB single-ended EVB

**Single-Ended Evaluation Board Performance Plots**



Test conditions unless otherwise noted:  $V_D = +48\text{ V}$ ,  $I_{DQ} = 600\text{ mA}$ ,  $T = 25^\circ\text{C}$ , on Class AB single-ended EVB

### RF Characterization – Power-Tuned Load Pull Performance

Frequency (MHz)	Source Impedance	Load Impedance	Gain @ P3dB (dB)	P3dB (dBm)	Drain Efficiency (%)
1800	6.21 – j1.70	6.15 – j5.81	15.1	55.4	54.0
1840	2.31 – j5.94	6.15 – j5.82	15.9	55.7	57.0
1880	4.21 – j2.56	6.00 – j4.30	16.4	55.7	62.5
2110	4.06 – j5.02	6.52 – j2.92	16.4	55.6	66.6
2140	4.24 – j5.12	8.50 – j2.10	15.7	55.6	59.4
2170	1.55 – j2.71	8.00 – j2.10	16.1	55.6	62.2

Test conditions unless otherwise noted:  $V_D = +48\text{ V}$ ,  $I_{DQ} = 600\text{ mA}$ ,  $T = 25^\circ\text{C}$ , Pulsed (10% duty cycle, 100  $\mu\text{s}$  width)

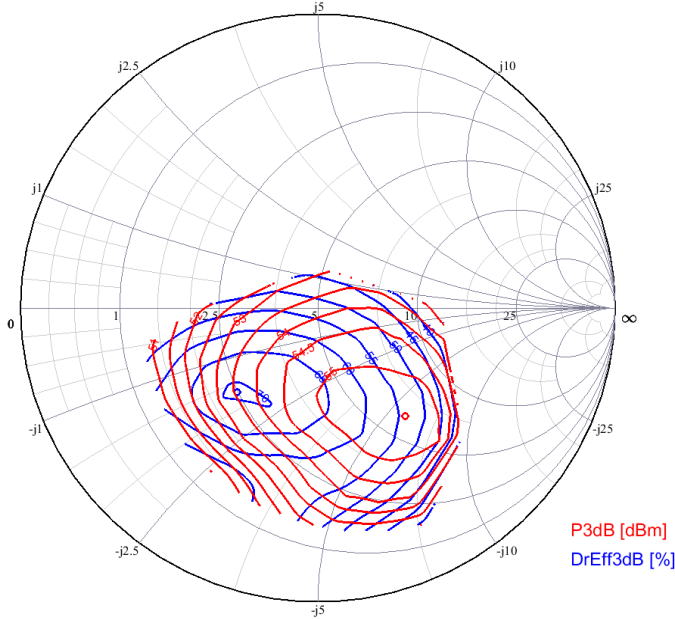
### RF Characterization – Efficiency-Tuned Load Pull Performance

Frequency (MHz)	Source Impedance	Load Impedance	Gain @ P3dB (dB)	P3dB (dBm)	Drain Efficiency (%)
1800	6.21 – j1.70	2.50 – j1.70	16.8	53.6	70.9
1840	2.31 – j5.94	2.92 – j2.22	17.6	54.3	73.3
1880	4.21 – j2.56	2.53 – j2.80	18.0	54.1	78.8
2110	4.06 – j5.02	2.14 – j3.38	17.6	52.6	78.4
2140	4.24 – j5.12	3.30 – j3.90	17.5	53.8	75.7
2170	1.55 – j2.71	2.23 – j4.27	18.0	52.2	77.7

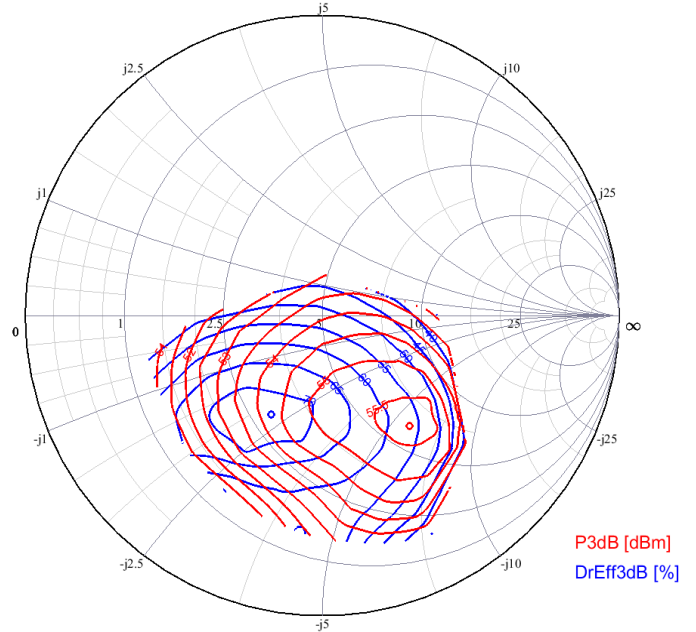
Test conditions unless otherwise noted:  $V_D = +48\text{ V}$ ,  $I_{DQ} = 600\text{ mA}$ ,  $T = 25^\circ\text{C}$ , Pulsed (10% duty cycle, 100  $\mu\text{s}$  width)

**Load Pull Plots**

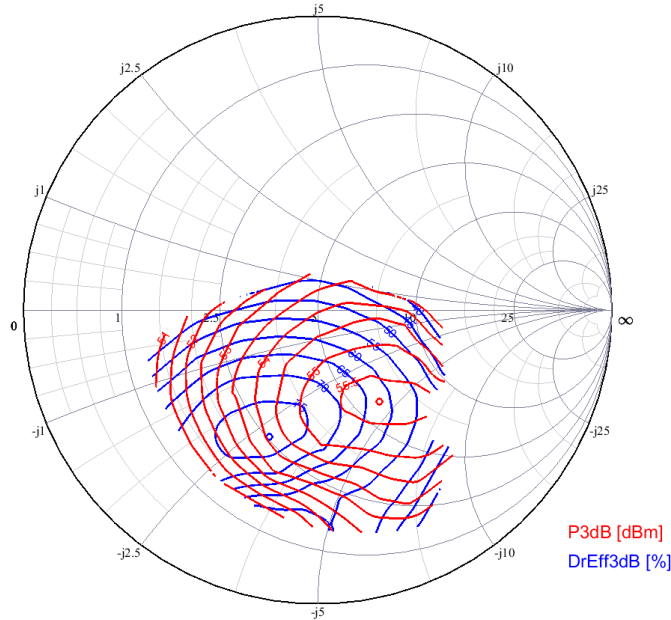
Load Pull at 1.8 GHz



Load Pull at 1.84 GHz



Load Pull at 1.88 GHz

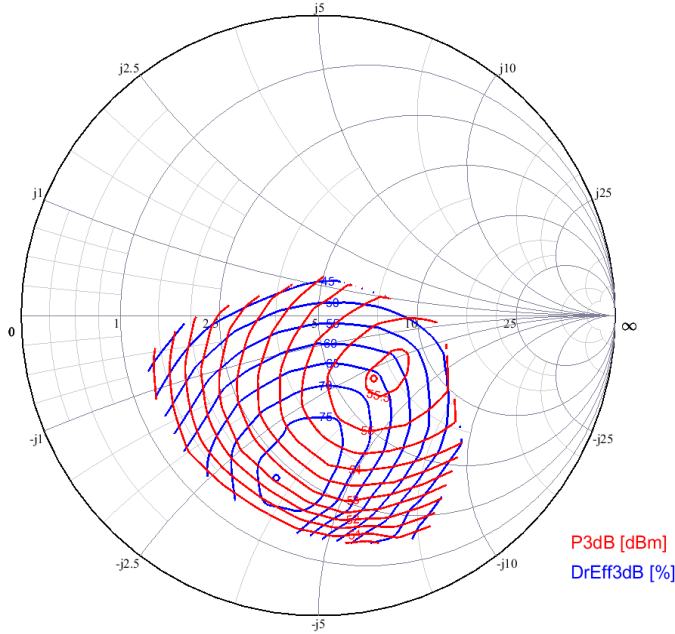


Test conditions unless otherwise noted:  $V_D = +48\text{ V}$ ,  $I_{DQ} = 600\text{ mA}$ ,  $T = 25^\circ\text{C}$ , Pulsed (10% duty cycle, 100  $\mu\text{s}$  width)

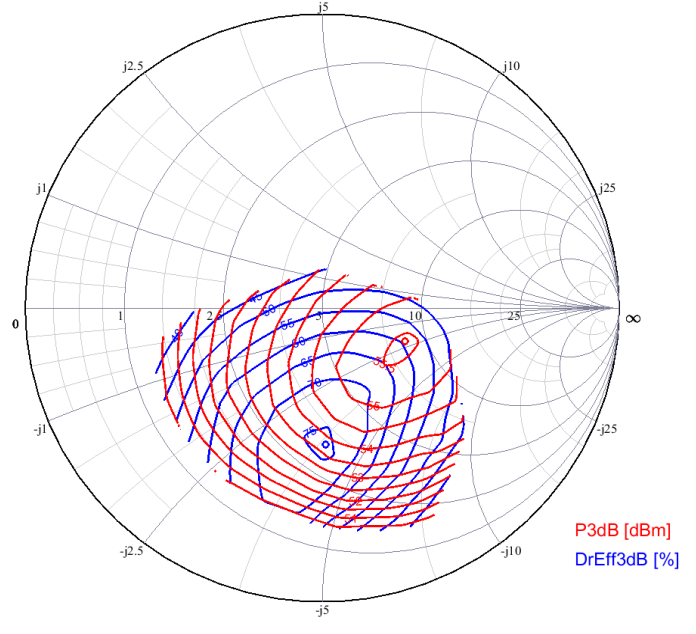


**Load Pull Plots**

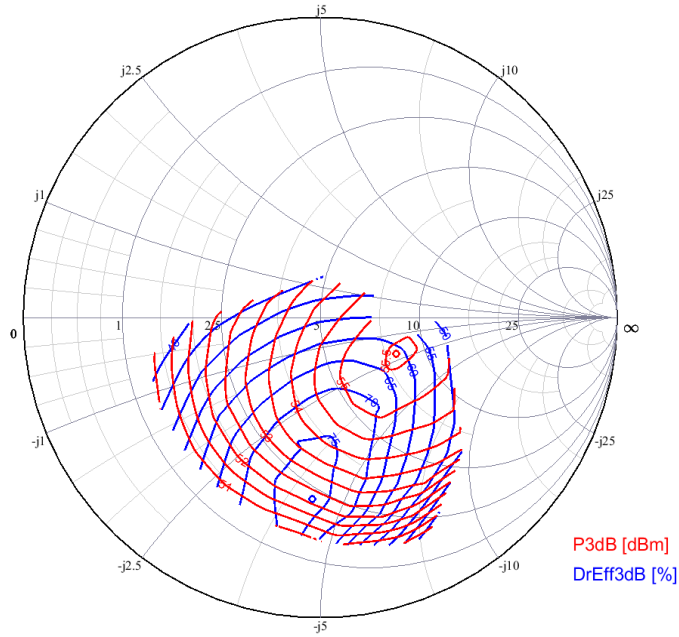
Load Pull at 2.11 GHz



Load Pull at 2.14 GHz

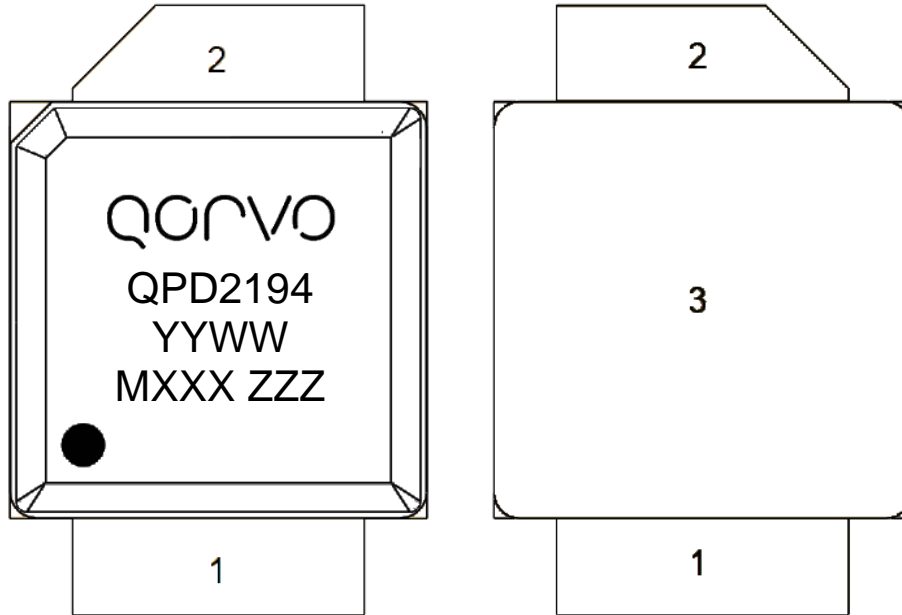


Load Pull at 2.17 GHz



Test conditions unless otherwise noted:  $V_D = +48\text{ V}$ ,  $I_{DQ} = 600\text{ mA}$ ,  $T = 25^\circ\text{C}$ , Pulsed (10% duty cycle, 100  $\mu\text{s}$  width)

## Pin Configuration

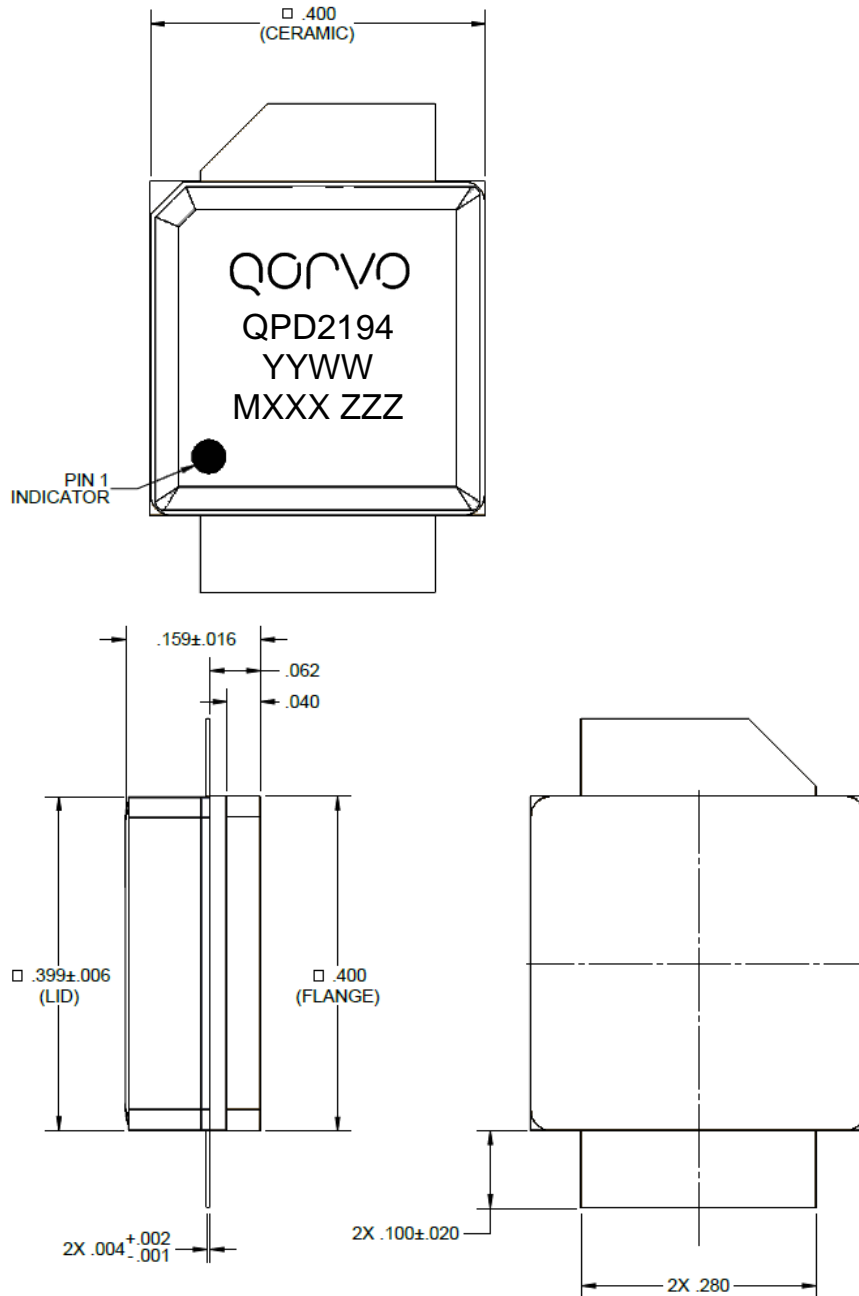


## Pin Description

Pin No.	Label	Description
1	RF IN, VG	RF Input, Gate Bias
2	RF OUT, VD	RF Output, Drain Bias
3 (Backside Paddle)	RF/DC GND	RF/DC Ground

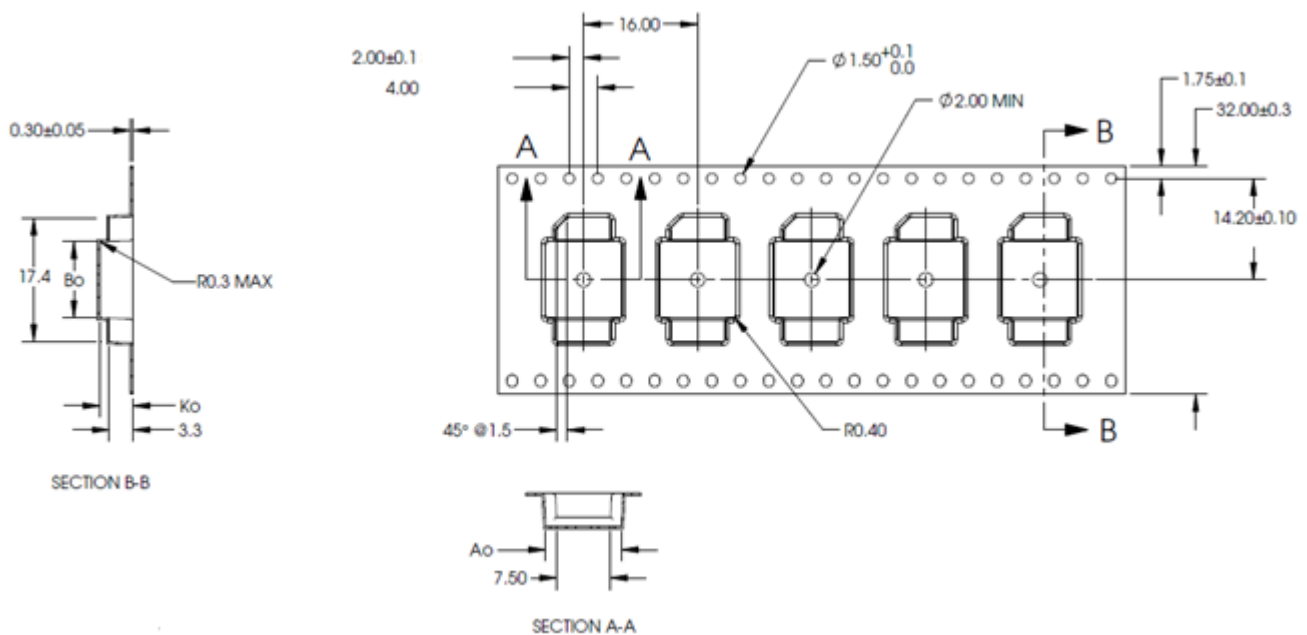
## Package Marking and Dimensions

Marking: Qorvo Logo  
 Part Number and Package Version – QPD2194  
 Date Code – YYWW  
 Production Lot Number – MXXX  
 Serial Number – ZZZ



Notes:  
 1. All dimensions are in inches. Angles are in degrees.  
 2. Exposed metallization is NiAu plated.

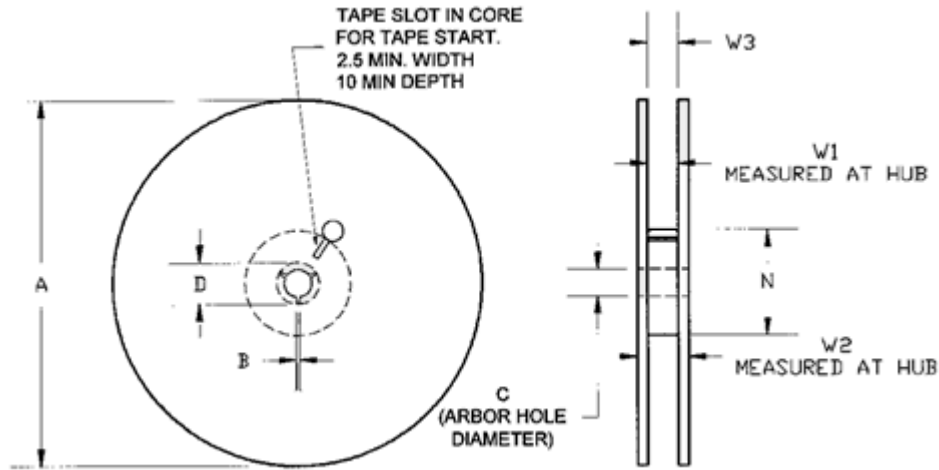
**Tape and Reel Information – Carrier and Cover Tape Dimensions**



Feature	Measure	Symbol	Size (in)	Size (mm)
Cavity	Length	A0	0.417	10.60
	Width	B0	0.419	10.65
	Depth	K0	0.181	4.60
	Pitch	P1	0.630	16
Centerline Distance	Cavity to Perforation – Length Direction	P2	0.079	2.00
	Cavity to Perforation – Width Direction	F	0.559	14.20
Cover Tape	Width	C	1.004	25.50
Carrier Tape	Width	W	1.260	32

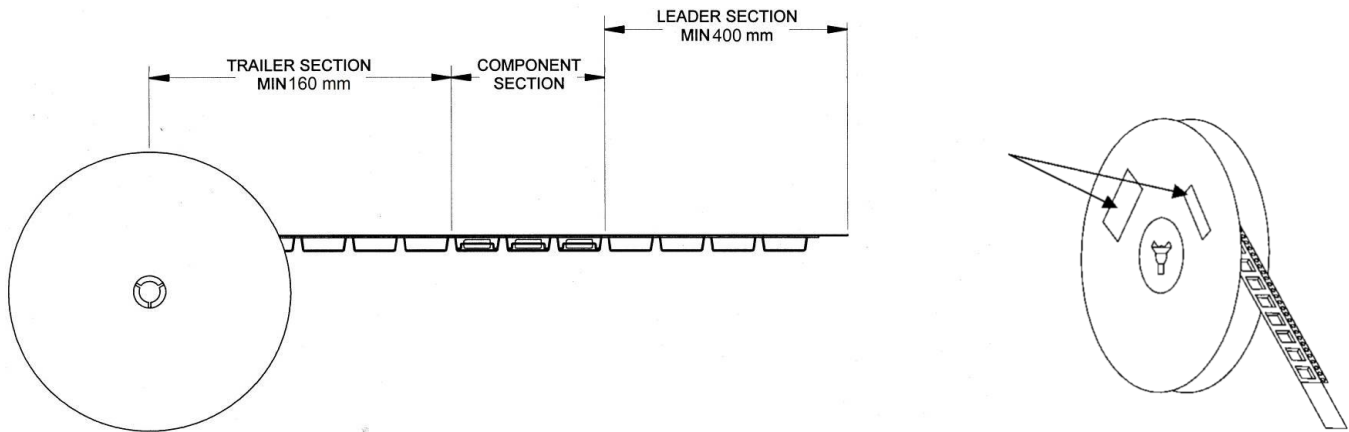
## Tape and Reel Information – Reel Dimensions

Standard T/R size = 100 pieces on a 13" reel.



Feature	Measure	Symbol	Size (in)	Size (mm)
Flange	Diameter	A	12.992	330.0
	Thickness	W2	1.504	38.2
	Space Between Flange	W1	1.291	32.8
Hub	Outer Diameter	N	4.016	102.0
	Arbor Hole Diameter	C	0.512	13.0
	Key Slit Width	B	0.079	2.0
	Key Slit Diameter	D	0.787	20.0

## Tape and Reel Information – Tape Length and Label Placement



**Notes:**

1. Empty part cavities at the trailing and leading ends are sealed with cover tape. See EIA 481-1-A.
2. Labels are placed on the flange opposite the sprockets in the carrier tape.

## Handling Precautions

Parameter	Rating	Standard
ESD – Human Body Model (HBM)	Class 1B	JEDEC Standard JESD22 A114
ESD – Charged Device Model (CDM)	Class C3	JEDEC Standard JESD22-C101F
MSL – 260°C Convection Reflow	Level 3	JEDEC standard IPC/JEDEC J-STD-020.



Caution!  
ESD-Sensitive Device

## Solderability

Compatible with both lead-free (260 °C maximum reflow temperature) and tin/lead (245 °C maximum reflow temperature) soldering processes.

The use of no-clean solder to avoid washing after soldering is recommended.

Contact plating: NiAu

## RoHS Compliance

This product is compliant with the 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment), as amended by Directive 2015/863/EU. This product also has the following attributes:

- Lead Free
- Antimony Free
- TBBP-A (C<sub>15</sub>H<sub>12</sub>Br<sub>4</sub>O<sub>2</sub>) Free
- PFOS Free
- SVHC Free

## Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about Qorvo:

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For technical questions and application information:

**Email:** [BTSApplications@qorvo.com](mailto:BTSApplications@qorvo.com)

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